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Atty. Dkt. No: AMK-11313

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: Donald Craig Foster

Application No.: 09/932,290

Art Unit.: 2827

Filing Date: 05/26/2004

Examiner: David E. Graybill

For: "Semiconductor Package And Leadframe With Horizontal Leads Spaced In The Vertical Direction And Method Of Making"

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Date: August 19, 2004

**AMENDMENT TRANSMITTAL**

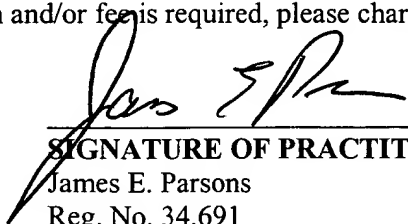
1. Transmitted herewith is an amendment for this application.
2. **STATUS:** Applicant is other than a small entity.
3. **EXTENSION OF TERM:** The proceedings herein are for a patent application and the provisions of 37 C.F.R. 1.136 apply. Applicant believes that no extension of term is required. However, this conditional petition is being made to provide for the possibility that applicant has inadvertently overlooked the need for a petition for extension of time.
4. **FEE FOR CLAIMS:** The fee for claims (37 C.F.R. 1.16(b)-(d)) has been calculated as shown below:

	(Col.1)		(Col. 2)		(Col. 3)	LARGE ENTITY	
	Claims Remaining After Amendment		Highest No. Previously Paid For		Present Extra	Rate	Addit. Fee
Total	52	Minus	52	= 0		x \$18 =	\$0
Indep.	5	Minus	5	= 0		x \$86 =	\$0
First Presentation of Multiple Dependent Claim						+ \$290 =	\$0
Total						Addit. Fee	\$0

**No additional fee for claims is required.**

5. **FEE DEFICIENCY:** If any additional extension and/or fee is required, please charge Deposit Account No. 50-0574.

Customer No. 022888  
Tel.: (408) 451-5900

  
**SIGNATURE OF PRACTITIONER**  
James E. Parsons  
Reg. No. 34,691

I hereby certify that this correspondence is being deposited with the United States Postal Service as FIRST CLASS MAIL in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on August 19, 2004.

Date: 8/19/2004  
Signature: Rebecca A. Baumann



THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Donald Craig Foster

Assignee: Amkor Technology, Inc.

Title: Semiconductor Package And Leadframe With  
Horizontal Leads Spaced In The Vertical Direction  
And Method Of Making

Serial No.: 09/932,290-4763 File Date: August 17, 2001

Examiner: Graybill, David E. Art Unit: 2827

Docket No.: AMK-11313 (formerly M-11313 US)

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Date: August 19, 2004

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE TO THE OFFICE ACTION OF 5/26/04**

Dear Sir:

In response to the Office Action mailed from the Patent Office on May 26, 2004, please amend the application as indicated below, and please consider the following remarks.